

**Technical Specifications**  
**Scanning Electron Microscope (SEM)**

S. No	Item	Specifications
1	Resolution	<ul style="list-style-type: none"> <li>• 2.0 nm at 30 kV or better in High Vacuum mode</li> <li>• 6.0 nm at 3 kV or better in High Vacuum mode</li> <li>• 9.0 nm at 1 kV or better in High Vacuum mode</li> <li>• 3.0 nm at 30 kV or better in Low Vacuum mode</li> </ul>
2	Magnification	<ul style="list-style-type: none"> <li>• 10x to 8,00,000x - continuously variable</li> </ul>
3	Accelerating Voltage	<ul style="list-style-type: none"> <li>• 0.2 kV to 30 kV, with incremental step of 10 volts for the entire range</li> </ul>
4	Probe Current	<ul style="list-style-type: none"> <li>• Up to 3 <math>\mu</math>A or more – continuously variable</li> </ul>
5	Electron Gun and Optics	<ul style="list-style-type: none"> <li>• LaB6 or W</li> </ul>
6	Vacuum and Imaging Modes	<ul style="list-style-type: none"> <li>• High Vacuum mode for conductive or coated specimens.</li> <li>• Extended environmental mode enabling stable imaging up to <math>\sim</math>3000 Pa to handle non-conductive, hydrated, or outgassing samples.</li> </ul>
7	Detectors	<ul style="list-style-type: none"> <li>• Secondary electron detector (ETSE) for high vacuum imaging</li> <li>• Back Scattered Electron Detector</li> <li>• Internal digital chamber camera</li> <li>• EDS detector</li> <li>• C2DX for VP Mode</li> </ul>
8	Specimen Stage	5-axes Fully Motorized Stage with movement facility with: <ul style="list-style-type: none"> <li>○ X = 90 mm or higher</li> <li>○ Y = 90 mm or higher</li> <li>○ Z = 50 mm or higher</li> <li>○ Tilt = <math>-10^{\circ}</math> to <math>+90^{\circ}</math></li> <li>○ Rotation = <math>360^{\circ}</math> - continuous</li> </ul>
9	Specimen Chamber	<ul style="list-style-type: none"> <li>• Maximum Sample size: 200 mm in diameter or better.</li> <li>• Maximum Sample height: 100 mm or better.</li> </ul>
10	Software Ability	<ul style="list-style-type: none"> <li>• Data acquisition and analysis</li> <li>• Automatic calibration of magnification and beam alignment</li> <li>• Automatic calibration of EDS</li> <li>• Drift-control system</li> <li>• On screen recording (video and image)</li> <li>• Auto as well as manual focusing, and aberration correction (AI enhanced), Auto and manual brightness and Contrast correction; Auto Gun alignment; Auto Beam alignment;</li> <li>• Micrograph analysis for identifying various features of micrograph</li> <li>• 3D viewing/ surface modelling</li> </ul>